

# MF15B-05 SEPA 5VDC 15x15x5mm Micro Cooling Axial Fan Datasheet



**Brand:** SEPA

**SKU:** [994756848187](#)

**Category:** Axial & Centrifugal Fans

**Price:** **\$19.99**

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Product Page:

<https://www.equipspares.com/product/mf15b-05-sepa-5vdc-15x15x5mm-micro-cooling-axial-fan>

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## Product Description

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The SEPA MF15B-05 is a Micro Axial Fan engineered for precision thermal management in ultra-compact electronic environments. Utilizing advanced DC brushless motor technology, this unit delivers consistent airflow while maintaining a minimal footprint, addressing the critical thermal impedance challenges found in high-density circuitry. The design incorporates a specialized aerodynamic blade geometry to maximize static pressure within the confined 15mm frame, ensuring efficient heat dissipation from sensitive components. Constructed with structural rigidity in mind, the fan operates with optimized stability, making it an essential component for maintaining the reliability and longevity of miniaturized industrial and computing systems.

Model Number: MF15B-05

Brand: SEPA

Product Type: Micro Axial Fan

Rated Voltage: 5VDC

Operating Voltage Range: 4.5 - 5.5 VDC

Rated Current: 0.06 A

Power Consumption: 0.30 W

Dimensions: 15 x 15 x 5 mm

Bearing Type: Sleeve Bearing

Termination: 2-Wire Lead

Motor Type: DC Brushless

Housing Material: Thermoplastic PBT (UL94V-0)

Blade Material: Thermoplastic PBT (UL94V-0)

Direction of Rotation: Counter-Clockwise

Mounting Style: Ribbed

Ingress Protection: Standard

Application: Micro-Server/Chipset Cooling

The MF15B-05 is specifically designed for applications where space is at an absolute premium but thermal reliability cannot be compromised. Common deployment scenarios include cooling specific chipsets on server motherboards, integrated cooling for handheld medical devices, and thermal regulation in compact optical equipment. The MF15B-05 ensures that localized hot spots in dense PCB layouts are effectively neutralized, preventing thermal throttling in critical embedded systems and miniature telecommunications hardware.

## Supplemental Images

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